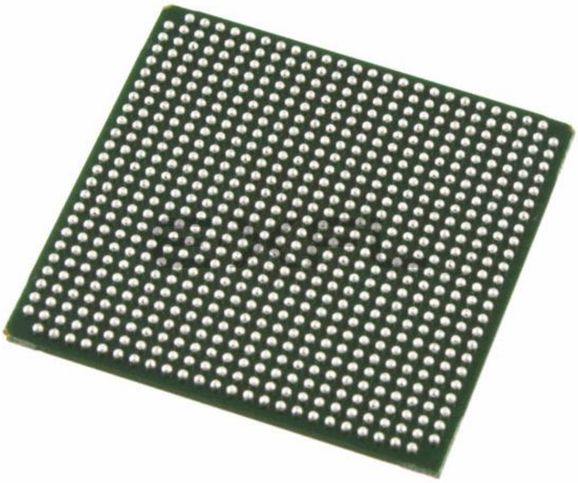
E·XFL Lattice Semiconductor Corporation - LFE2-20SE-7FN672C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	2625
Number of Logic Elements/Cells	21000
Total RAM Bits	282624
Number of I/O	402
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-20se-7fn672c

LatticeECP2/M Family Data Sheet Introduction

July 2012 **Data Sheet DS1006**

Features

- **High Logic Density for System Integration**
  - 6K to 95K LUTs
  - 90 to 583 I/Os
- **Embedded SERDES (LatticeECP2M Only)**
  - Data Rates 250 Mbps to 3.125 Gbps
  - Up to 16 channels per device PCI Express, Ethernet (1GbE, SGMII), OBSAI, CPRI and Serial RapidIO.
- **sysDSP™ Block**
  - 3 to 42 blocks for high performance multiply and accumulate
  - Each block supports
    - One 36x36, four 18x18 or eight 9x9 multipliers
- **Flexible Memory Resources**
  - 55Kbits to 5308Kbits sysMEM™ Embedded Block RAM (EBR)
    - 18Kbit block
    - Single, pseudo dual and true dual port
    - Byte Enable Mode support
  - 12K to 202Kbits distributed RAM
    - Single port and pseudo dual port
- **sysCLOCK Analog PLLs and DLLs**
  - Two GPLLs and up to six SPLLs per device
    - Clock multiply, divide, phase & delay adjust
    - Dynamic PLL adjustment
  - Two general purpose DLLs per device
- **Pre-Engineered Source Synchronous I/O**
  - DDR registers in I/O cells
  - Dedicated gearing logic
  - Source synchronous standards support
    - SPI4.2, SFI4 (DDR Mode), XGMII
    - High Speed ADC/DAC devices
  - Dedicated DDR and DDR2 memory support
    - DDR1: 400 (200MHz) / DDR2: 533 (266MHz)
  - Dedicated DQS support
- **Programmable sysI/O™ Buffer Supports Wide Range Of Interfaces**
  - LVTTL and LVCMOS 33/25/18/15/12
  - SSTL 3/2/18 I, II
  - HSTL15 I and HSTL18 I, II
  - PCI and Differential HSTL, SSTL
  - LVDS, RSDS, Bus-LVDS, MLVDS, LVPECL
- **Flexible Device Configuration**
  - 1149.1 Boundary Scan compliant
  - Dedicated bank for configuration I/Os
  - SPI boot flash interface
  - Dual boot images supported
  - TransFR™ I/O for simple field updates
  - Soft Error Detect macro embedded
- **Optional Bitstream Encryption (LatticeECP2/M "S" Versions Only)**
- **System Level Support**
  - ispTRACY™ internal logic analyzer capability
  - On-chip oscillator for initialization & general use
  - 1.2V power supply

Table 1-1. LatticeECP2 (Including "S-Series") Family Selection

Device	ECP2-6	ECP2-12	ECP2-20	ECP2-35	ECP2-50	ECP2-70
LUTs (K)	6	12	21	32	48	68
Distributed RAM (Kbits)	12	24	42	64	96	136
EBR SRAM (Kbits)	55	221	276	332	387	1032
EBR SRAM Blocks	3	12	15	18	21	60
sysDSP Blocks	3	6	7	8	18	22
18x18 Multipliers	12	24	28	32	72	88
GPLL + SPLL + DLL	2+0+2	2+0+2	2+0+2	2+0+2	2+2+2	2+4+2
Maximum Available I/O	190	297	402	450	500	583
Packages and I/O Combinations						
144-pin TQFP (20 x 20 mm)	90	93				
208-pin PQFP (28 x 28 mm)		131	131			
256-ball fpBGA (17 x 17 mm)	190	193	193			
484-ball fpBGA (23 x 23 mm)		297	331	331	339	
672-ball fpBGA (27 x 27 mm)			402	450	500	500
900-ball fpBGA (31 x 31 mm)						583

sets of single-ended input buffers (both ratioed and referenced). One of the referenced input buffers can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

3. **Left and Right (Banks 2, 3, 6 and 7) sysI/O Buffer Pairs (50% Differential and 100% Single-Ended Outputs)**
The sysI/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. One of the referenced input buffers can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   LVDS differential output drivers are available on 50% of the buffer pairs on the left and right banks.

4. **Bank 8 sysI/O Buffer Pairs (Single-Ended Outputs, Only on Shared Pins When Not Used by Configuration)**
The sysI/O buffers in Bank 8 consist of single-ended output drivers and single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

In LatticeECP2 devices, only the I/Os on the bottom banks have programmable PCI clamps. In LatticeECP2M devices, the I/Os on the left and bottom banks have programmable PCI clamps.

Typical sysI/O I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC}, V_{CCIO8} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user’s responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. For more information about controlling the output logic state with valid input logic levels during power-up in LatticeECP2/M devices, see the list of additional technical documentation at the end of this data sheet.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered-up before or together with the V_{CC} and V_{CCAUX} supplies.

Prior to and throughout programming of the FPGA, the I/O of the device have a weak-pullup resistor to V_{CCIO} on the input buffer and the output buffer is tri-stated. A pullup to V_{CCIO} is present on the input until the user programs the input differently in the FPGA design. See the DC Electrical Characteristics table of this data sheet. The pullup value will be between 20-30K ohms based on the V_{CCIO} voltage supplied on the board. This pullup will also remain active if the design does not use a particular I/O.

Supported sysI/O Standards

The LatticeECP2/M sysI/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2V, 1.5V, 1.8V, 2.5V and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individual configuration options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, MLVDS, BLVDS, LVPECL, RSDS, differential SSTL and differential HSTL. Tables 2-13 and 2-14 show the I/

SERDES and PCS (Physical Coding Sublayer)

LatticeECP2M devices feature up to 16 channels of embedded SERDES arranged in quads at the corners of the devices. Figure 2-39 shows the position of the quad blocks in relation to the PFU array for LatticeECP2M70 and LatticeECP2M100 devices. Table 2-15 shows the location of Quads for all the devices.

Each quad contains four dedicated SERDES (Ch0 to Ch3) for high-speed, full-duplex serial data transfer. Each quad also has a PCS block that interfaces to the SERDES channels and contains digital logic to support an array of popular data protocols. PCS also contains logic to the interface to FPGA core.

Figure 2-39. SERDES Quads (LatticeECP2M70/LatticeECP2M100)

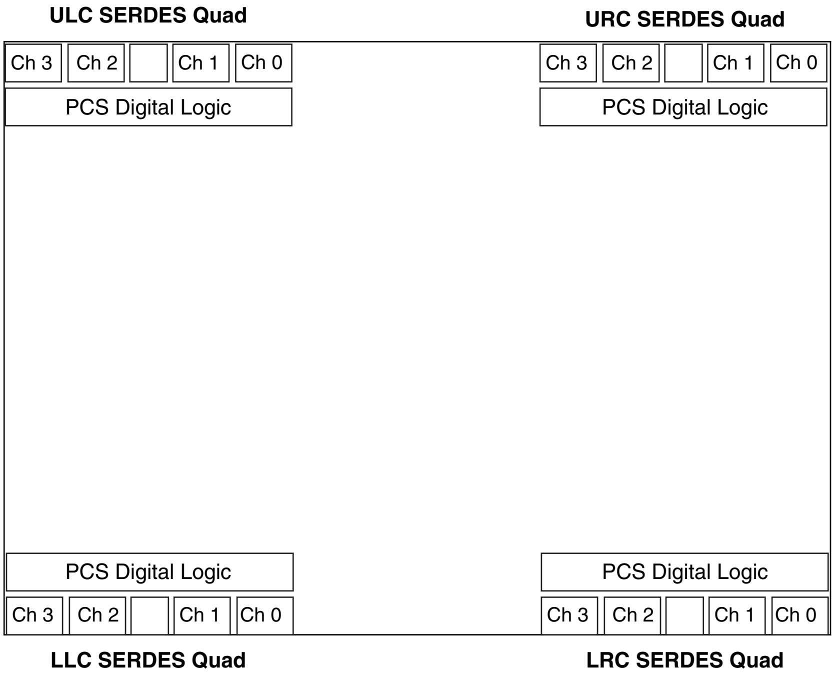

Table 2-15. Available SERDES Quads per LatticeECP2M Devices

Device	URC Quad	ULC Quad	LRC Quad	LLC Quad
ECP2M20	Available	—	—	—
ECP2M35	Available	—	—	—
ECP2M50	Available	—	Available	—
ECP2M70	Available	Available	Available	Available
ECP2M100	Available	Available	Available	Available

SERDES Block

A differential receiver receives the serial encoded data stream, equalizes the signal, extracts the buried clock and de-serializes the data-stream before passing the 8- or 10-bit data to the PCS logic. The transmit channel receives the parallel (8- or 10-bit) encoded data, serializes the data and transmits the serial bit stream through the differential buffers. There is a single transmit clock per quad. Figure 2-40 shows a single channel SERDES and its interface to the PCS logic. Each SERDES receiver channel provides a recovered clock to the PCS block and to the FPGA core logic.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In- System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, LatticeECP2/M sysCONFIG Usage Guide for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. **Decryption Support**
   LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. **TransFR (Transparent Field Reconfiguration)**
   TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology, for details.

3. **Dual Boot Image Support**
   Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed

MLVDS

The LatticeECP2/M devices support the differential MLVDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The MLVDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-5 is one possible solution for MLVDS standard implementation. Resistor values in Figure 3-5 are industry standard values for 1% resistors.

Figure 3-5. MLVDS (Multipoint Low Voltage Differential Signaling)

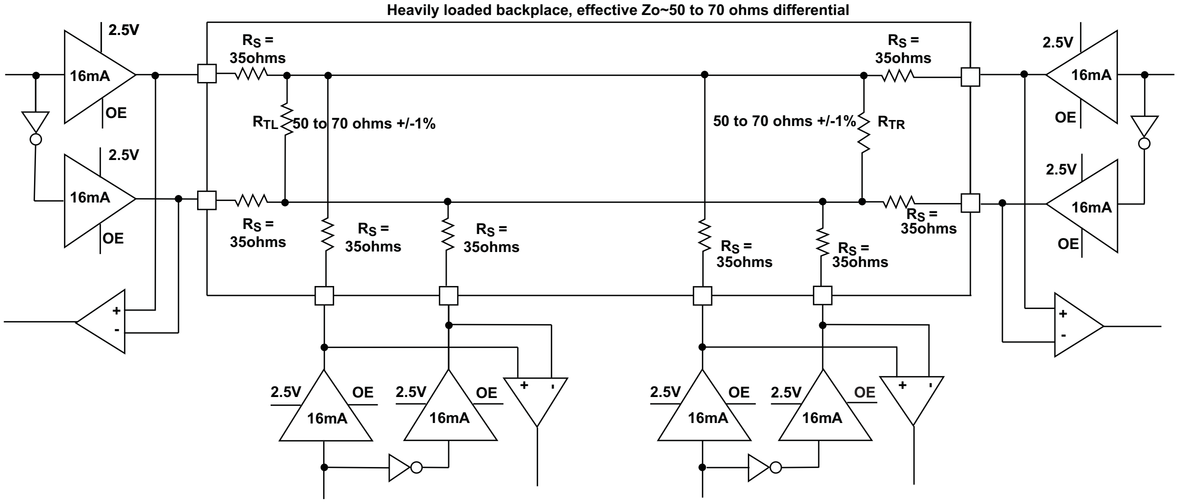

Table 3-6. MLVDS DC Conditions[1]

Parameter	Description	Typical		Units
		Zo=50Ω	Zo=70Ω	
V_{CCIO}	Output Driver Supply (+/-5%)	2.50	2.50	V
Z_{OUT}	Driver Impedance	10.00	10.00	Ω
R_S	Driver Series Resistor (+/-1%)	35.00	35.00	Ω
R_{TL}	Driver Parallel Resistor (+/-1%)	50.00	70.00	Ω
R_{TR}	Receiver Termination (+/-1%)	50.00	70.00	Ω
V_{OH}	Output High Voltage	1.52	1.60	V
V_{OL}	Output Low Voltage	0.98	0.90	V
V_{OD}	Output Differential Voltage	0.54	0.70	V
V_{CM}	Output Common Mode Voltage	1.25	1.25	V
I_{DC}	DC Output Current	21.74	20.00	mA

1. For input buffer, see LVDS table.

For further information about LVPECL, RSDS, MLVDS, BLVDS and other differential interfaces please see the list of additional technical information at the end of this data sheet.

Typical Building Block Function Performance[1]

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-7 Timing	Units
Basic Functions		
16-bit Decoder	3.8	ns
32-bit Decoder	4.5	ns
64-bit Decoder	5.0	ns
4:1 MUX	3.2	ns
8:1 MUX	3.4	ns
16:1 MUX	3.5	ns
32:1 MUX	4.0	ns

1. These timing numbers were generated using the ispLEVER 8.0 design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Register-to-Register Performance

Function	-7 Timing	Units
Basic Functions		
16-bit Decoder	599	MHz
32-bit Decoder	542	MHz
64-bit Decoder	417	MHz
4:1 MUX	847	MHz
8:1 MUX	803	MHz
16:1 MUX	660	MHz
32:1 MUX	577	MHz
8-bit Adder	591	MHz
16-bit Adder	500	MHz
64-bit Adder	306	MHz
16-bit Counter	488	MHz
32-bit Counter	378	MHz
64-bit Counter	260	MHz
64-bit Accumulator	253	MHz
Embedded Memory Functions		
512x36 Single Port RAM, EBR Output Registers	370	MHz
1024x18 True-Dual Port RAM (Write Through or Normal, EBR Output Registers)	370	MHz
1024x18 True-Dual Port RAM (Write Through or Normal, PLC Output Registers)	280	MHz
Distributed Memory Functions		
16x4 Pseudo-Dual Port RAM (One PFU)	819	MHz
32x4 Pseudo-Dual Port RAM	521	MHz
64x8 Pseudo-Dual Port RAM	435	MHz
DSP Functions		
18x18 Multiplier (All Registers)	420	MHz
9x9 Multiplier (All Registers)	420	MHz

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N14	CFG1	8			CFG1	8		
N13	PROGRAMN	8			PROGRAMN	8		
N15	CFG0	8			CFG0	8		
P15	PR30B	8	WRITEN	C	PR30B	8	WRITEN	C
L12	INITN	8			INITN	8		
N16	PR29B	8	CSN	C	PR29B	8	CSN	C
GND	GNDIO8	-			GNDIO8	-		
R14	CCLK	8			CCLK	8		
P14	PR30A	8	CS1N	T	PR30A	8	CS1N	T
M13	DONE	8			DONE	8		
R16	PR28B	8	D1	C	PR28B	8	D1	C
VCCIO	VCCIO8	8			VCCIO8	8		
M16	PR29A	8	D0/SPIFASTN	T	PR29A	8	D0/SPIFASTN	T
P16	PR28A	8	D2	T	PR28A	8	D2	T
L15	PR27B	8	D3	C	PR27B	8	D3	C
GND	GNDIO8	-			GNDIO8	-		
L14	PR26A	8	D6	T	PR26A	8	D6	T
L16	PR27A	8	D4	T	PR27A	8	D4	T
L10	PR25B	8	D7/SPID0	C	PR25B	8	D7/SPID0	C
L13	PR26B	8	D5	C	PR26B	8	D5	C
VCCIO	VCCIO8	8			VCCIO8	8		
K11	PR25A	8	DI/CSSPI0N	T	PR25A	8	DI/CSSPI0N	T
K14	PR24B	8	DOUT/CSON	C	PR24B	8	DOUT/CSON	C
K13	PR24A	8	BUSY/SISPI	T	PR24A	8	BUSY/SISPI	T
GND	GNDIO8	-			GNDIO8	-		
K15	PR21B	3	RLM0_GPLLC_FB_A	C	PR21B	3	RLM0_GPLLC_FB_A	C
VCCIO	VCCIO3	3			VCCIO3	3		
K16	PR21A	3	RLM0_GPLLT_FB_A	T	PR21A	3	RLM0_GPLLT_FB_A	T
GND	GNDIO3	-			GNDIO3	-		
J16	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*
J15	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*
J14	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
J13	PR18B	3	RLM0_GDLLC_FB_A	C	PR18B	3	RLM0_GDLLC_FB_A	C
J12	PR18A	3	RLM0_GDLLT_FB_A	T	PR18A	3	RLM0_GDLLT_FB_A	T
H12	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*
GND	GNDIO3	-			GNDIO3	-		
H13	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*
H15	PR16B	3	VREF2_3	C	PR16B	3	VREF2_3	C
VCCIO	VCCIO3	3			VCCIO3	3		
H16	PR16A	3	VREF1_3	T	PR16A	3	VREF1_3	T
H11	PR15B	3	PCLKC3_0	C (LVDS)*	PR15B	3	PCLKC3_0	C (LVDS)*
J11	PR15A	3	PCLKT3_0	T (LVDS)*	PR15A	3	PCLKT3_0	T (LVDS)*
G16	PR13B	2	PCLKC2_0/RDQ10	C	PR13B	2	PCLKC2_0/RDQ10	C
GND	GNDIO2	-			GNDIO2	-		
G15	PR13A	2	PCLKT2_0/RDQ10	T	PR13A	2	PCLKT2_0/RDQ10	T

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
-	-	-			GNDIO1	1		
-	-	-			VCCIO	1		
D10	PT19B	1		C	PT37B	1		C
C10	PT19A	1		T	PT37A	1		T
GND	GNDIO1	-			GNDIO1	-		
B10	PT18B	1		C	PT36B	1		C
A9	PT17B	1		C	PT35B	1		C
A10	PT18A	1		T	PT36A	1		T
B9	PT17A	1		T	PT35A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A8	PT16B	1		C	PT34B	1		C
D9	PT15B	1		C	PT33B	1		C
B8	PT16A	1		T	PT34A	1		T
C9	PT15A	1		T	PT33A	1		T
GND	GNDIO1	-			GNDIO1	-		
B7	PT14B	1		C	PT32B	1		C
E9	PT13B	1		C	PT31B	1		C
A7	PT14A	1		T	PT32A	1		T
D8	PT13A	1		T	PT31A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A6	PT12B	1	PCLKC1_0	C	PT30B	1	PCLKC1_0	C
B6	PT12A	1	PCLKT1_0	T	PT30A	1	PCLKT1_0	T
E6	XRES	-			XRES	1		
F8	PT10B	0	PCLKC0_0	C	PT28B	0	PCLKC0_0	C
GND	GNDIO0	-			GNDIO0	-		
E8	PT10A	0	PCLKT0_0	T	PT28A	0	PCLKT0_0	T
A5	PT9B	0		C	PT27B	0		C
A3	PT8B	0		C	PT26B	0		C
A4	PT9A	0		T	PT27A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
B3	PT8A	0		T	PT26A	0		T
A2	PT7B	0		C	PT25B	0		C
C7	PT6B	0		C	PT24B	0		C
B2	PT7A	0		T	PT25A	0		T
D7	PT6A	0		T	PT24A	0		T
D6	PT5B	0		C	PT23B	0		C
GND	GNDIO0	-			GNDIO0	-		
F7	PT4B	0		C	PT22B	0		C
C6	PT5A	0		T	PT23A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F6	PT4A	0		T	PT22A	0		T
C4	PT3B	0		C	PT21B	0		C
B4	PT3A	0		T	PT21A	0		T
-	-	-			GNDIO0	0		
-	-	-			VCCIO	0		

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

	LFE2-6E/SE				LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D5	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
E5	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T
G7	VCC	-			VCC	-		
G9	VCC	-			VCC	-		
H7	VCC	-			VCC	-		
J10	VCC	-			VCC	-		
K10	VCC	-			VCC	-		
K8	VCC	-			VCC	-		
G8	VCCAUX	-			VCCAUX	-		
H10	VCCAUX	-			VCCAUX	-		
J7	VCCAUX	-			VCCAUX	-		
K9	VCCAUX	-			VCCAUX	-		
C5	VCCIO0	0			VCCIO0	0		
E7	VCCIO0	0			VCCIO0	0		
C12	VCCIO1	1			VCCIO1	1		
E10	VCCIO1	1			VCCIO1	1		
E14	VCCIO2	2			VCCIO2	2		
G12	VCCIO2	2			VCCIO2	2		
K12	VCCIO3	3			VCCIO3	3		
M14	VCCIO3	3			VCCIO3	3		
M10	VCCIO4	4			VCCIO4	4		
P12	VCCIO4	4			VCCIO4	4		
M7	VCCIO5	5			VCCIO5	5		
P5	VCCIO5	5			VCCIO5	5		
K5	VCCIO6	6			VCCIO6	6		
M3	VCCIO6	6			VCCIO6	6		
E3	VCCIO7	7			VCCIO7	7		
G5	VCCIO7	7			VCCIO7	7		
T15	VCCIO8	8			VCCIO8	8		
A1	GND	-			GND	-		
A16	GND	-			GND	-		
B12	GND	-			GND	-		
B5	GND	-			GND	-		
C8	GND	-			GND	-		
E15	GND	-			GND	-		
E2	GND	-			GND	-		
H14	GND	-			GND	-		
H8	GND	-			GND	-		
H9	GND	-			GND	-		
J3	GND	-			GND	-		
J8	GND	-			GND	-		
J9	GND	-			GND	-		
M15	GND	-			GND	-		
M2	GND	-			GND	-		
P9	GND	-			GND	-		

LFE2-20E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
VCCIO	VCCIO	VCCIO1	1		
D12	D12	PT62A	1		T
B14	B14	PT61B	1		C
C14	C14	PT60B	1		C
A14	A14	PT61A	1		T
D13	D13	PT60A	1		T
C13	C13	PT59B	1		C
GND	GND	GNDIO1	-		
A13	A13	PT58B	1		C
B13	B13	PT59A	1		T
VCCIO	VCCIO	VCCIO1	1		
A12	A12	PT58A	1		T
B11	B11	PT57B	1		C
D11	D11	PT56B	1		C
A11	A11	PT57A	1		T
C11	C11	PT56A	1		T
-	GND	GNDIO1	1		
-	VCC	VCCIO	1		
D10	D10	PT46B	1		C
C10	C10	PT46A	1		T
GND	GND	GNDIO1	-		
B10	B10	PT45B	1		C
A9	A9	PT44B	1		C
A10	A10	PT45A	1		T
B9	B9	PT44A	1		T
VCCIO	VCCIO	VCCIO1	1		
A8	A8	PT43B	1		C
D9	D9	PT42B	1		C
B8	B8	PT43A	1		T
C9	C9	PT42A	1		T
GND	GND	GNDIO1	-		
B7	B7	PT41B	1		C
E9	E9	PT40B	1		C
A7	A7	PT41A	1		T
D8	D8	PT40A	1		T
VCCIO	VCCIO	VCCIO1	1		
A6	A6	PT39B	1	PCLKC1_0	C
B6	B6	PT39A	1	PCLKT1_0	T
E6	E6	XRES	1		
F8	F8	PT37B	0	PCLKC0_0	C
GND	GND	GNDIO0	-		
E8	E8	PT37A	0	PCLKT0_0	T

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AB7	PB13B	5	BDQ15	C	PB22B	5	BDQ24	C
Y8	PB16A	5	BDQ15	T	PB25A	5	BDQ24	T
GNDIO	GNDIO5	-			GNDIO	-		
W9	PB15A	5	BDQS15	T	PB24A	5	BDQS24	T
AA8	PB16B	5	BDQ15	C	PB25B	5	BDQ24	C
V9	PB15B	5	BDQ15	C	PB24B	5	BDQ24	C
AB8	PB18A	5	BDQ15	T	PB27A	5	BDQ24	T
VCCIO	VCCIO5	5			VCCIO5	5		
W10	PB17A	5	BDQ15	T	PB26A	5	BDQ24	T
AA9	PB18B	5	BDQ15	C	PB27B	5	BDQ24	C
V10	PB17B	5	BDQ15	C	PB26B	5	BDQ24	C
GNDIO	GNDIO5	-			GNDIO	-		
Y10	PB21A	5	BDQ24	T	PB30A	5	BDQ33	T
AB9	PB20A	5	BDQ24	T	PB29A	5	BDQ33	T
AA10	PB21B	5	BDQ24	C	PB30B	5	BDQ33	C
AB10	PB20B	5	BDQ24	C	PB29B	5	BDQ33	C
AB11	PB23A	5	BDQ24	T	PB32A	5	BDQ33	T
U10	PB22A	5	BDQ24	T	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AA11	PB23B	5	BDQ24	C	PB32B	5	BDQ33	C
U11	PB22B	5	BDQ24	C	PB31B	5	BDQ33	C
GNDIO	GNDIO5	-			GNDIO5	-		
AB12	PB25A	5	BDQ24	T	PB34A	5	BDQ33	T
Y11	PB24A	5	BDQS24	T	PB33A	5	BDQS33	T
AA12	PB25B	5	BDQ24	C	PB34B	5	BDQ33	C
W11	PB24B	5	BDQ24	C	PB33B	5	BDQ33	C
AB13	PB26A	5	PCLKT5_0/BDQ24	T	PB35A	5	PCLKT5_0/BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AB14	PB26B	5	PCLKC5_0/BDQ24	C	PB35B	5	PCLKC5_0/BDQ33	C
GNDIO	GNDIO5	-			GNDIO5	-		
Y12	PB32A	4	BDQ33	T	PB41A	4	BDQ42	T
W12	PB32B	4	BDQ33	C	PB41B	4	BDQ42	C
VCCIO	VCCIO4	4			VCCIO4	4		
U12	PB31A	4	PCLKT4_0/BDQ33	T	PB40A	4	PCLKT4_0/BDQ42	T
V12	PB31B	4	PCLKC4_0/BDQ33	C	PB40B	4	PCLKC4_0/BDQ42	C
U13	PB34A	4	BDQ33	T	PB43A	4	BDQ42	T
GNDIO	GNDIO4	-			GNDIO4	-		
AA13	PB33A	4	BDQS33	T	PB42A	4	BDQS42	T
U14	PB34B	4	BDQ33	C	PB43B	4	BDQ42	C
Y13	PB33B	4	BDQ33	C	PB42B	4	BDQ42	C
AB16	PB36A	4	BDQ33	T	PB45A	4	BDQ42	T
VCCIO	VCCIO4	4			VCCIO4	4		
AB15	PB35A	4	BDQ33	T	PB44A	4	BDQ42	T
AB17	PB36B	4	BDQ33	C	PB45B	4	BDQ42	C

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
U1	NC	-			PL34A	6	LDQ31	T
V1	NC	-			PL34B	6	LDQ31	C
GND	GNDIO6	-			GNDIO6	-		
P3	NC	-			NC	-		
R3	NC	-			NC	-		
R4	NC	-			NC	-		
U2	NC	-			NC	-		
VCCIO	VCCIO6	6			VCCIO6	6		
V2	NC	-			NC	-		
W2	NC	-			NC	-		
T6	NC	-			PL38A	6	LDQ39	T
R5	NC	-			PL38B	6	LDQ39	C
GND	GNDIO6	-			GNDIO6	-		
R6	PL25A	6	LDQS25***	T (LVDS)*	PL39A	6	LDQS39***	T (LVDS)*
R7	PL25B	6	LDQ25	C (LVDS)*	PL39B	6	LDQ39	C (LVDS)*
W1	PL26A	6	LDQ25	T	PL40A	6	LDQ39	T
VCCIO	VCCIO6	6			VCCIO6	6		
Y2	PL26B	6	LDQ25	C	PL40B	6	LDQ39	C
Y1	PL27A	6	LLM0_GDLLT_IN_A**/LDQ25	T (LVDS)*	PL41A	6	LLM0_GDLLT_IN_A**/LDQ39	T (LVDS)*
AA2	PL27B	6	LLM0_GDLLC_IN_A**/LDQ25	C (LVDS)*	PL41B	6	LLM0_GDLLC_IN_A**/LDQ39	C (LVDS)*
T5	PL28A	6	LLM0_GDLLT_FB_A/LDQ25	T	PL42A	6	LLM0_GDLLT_FB_A/LDQ39	T
GND	GNDIO6	-			GNDIO6	-		
T7	PL28B	6	LLM0_GDLLC_FB_A/LDQ25	C	PL42B	6	LLM0_GDLLC_FB_A/LDQ39	C
R8	VCC	6			VCCPLL	6		
T8	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
U3	PL30A	6	LLM0_GPLLT_IN_A**/LDQ34	T (LVDS)*	PL44A	6	LLM0_GPLLT_IN_A**/LDQ48	T (LVDS)*
U4	PL30B	6	LLM0_GPLLC_IN_A**/LDQ34	C (LVDS)*	PL44B	6	LLM0_GPLLC_IN_A**/LDQ48	C (LVDS)*
V3	PL31A	6	LLM0_GPLLT_FB_A/LDQ34	T	PL45A	6	LLM0_GPLLT_FB_A/LDQ48	T
U5	PL31B	6	LLM0_GPLLC_FB_A/LDQ34	C	PL45B	6	LLM0_GPLLC_FB_A/LDQ48	C
V4	PL32A	6	LDQ34	T (LVDS)*	PL46A	6	LDQ48	T (LVDS)*
VCCIO	VCCIO6	6			VCCIO6	6		
V5	PL32B	6	LDQ34	C (LVDS)*	PL46B	6	LDQ48	C (LVDS)*
Y3	PL33A	6	LDQ34	T	PL47A	6	LDQ48	T
Y4	PL33B	6	LDQ34	C	PL47B	6	LDQ48	C
W3	PL34A	6	LDQS34	T (LVDS)*	PL48A	6	LDQS48	T (LVDS)*
GND	GNDIO6	-			GNDIO6	-		
W4	PL34B	6	LDQ34	C (LVDS)*	PL48B	6	LDQ48	C (LVDS)*
AA1	PL35A	6	LDQ34	T	PL49A	6	LDQ48	T
AB1	PL35B	6	LDQ34	C	PL49B	6	LDQ48	C
VCCIO	VCCIO6	6			VCCIO6	6		
U8	PL36A	6	LDQ34	T (LVDS)*	PL50A	6	LDQ48	T (LVDS)*
U7	PL36B	6	LDQ34	C (LVDS)*	PL50B	6	LDQ48	C (LVDS)*
V8	PL37A	6	LDQ34	T	PL51A	6	LDQ48	T
U6	PL37B	6	LDQ34	C	PL51B	6	LDQ48	C
GND	GNDIO6	-			GNDIO6	-		
W6	PL38A	6	LDQ42	T (LVDS)*	PL52A	6	LDQ56	T (LVDS)*

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA14	PB29B	5	BDQ33	C	PB29B	5	BDQ33	C
AE10	PB30A	5	BDQ33	T	PB30A	5	BDQ33	T
AF10	PB30B	5	BDQ33	C	PB30B	5	BDQ33	C
W14	PB31A	5	BDQ33	T	PB31A	5	BDQ33	T
AB13	PB31B	5	BDQ33	C	PB31B	5	BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
Y14	PB32A	5	BDQ33	T	PB32A	5	BDQ33	T
AB14	PB32B	5	BDQ33	C	PB32B	5	BDQ33	C
GND	GNDIO5	-			GNDIO5	-		
AE11	PB33A	5	BDQS33	T	PB33A	5	BDQS33	T
AF11	PB33B	5	BDQ33	C	PB33B	5	BDQ33	C
AD14	PB34A	5	BDQ33	T	PB34A	5	BDQ33	T
AA15	PB34B	5	BDQ33	C	PB34B	5	BDQ33	C
AE12	PB35A	5	PCLKT5_0/BDQ33	T	PB35A	5	PCLKT5_0/BDQ33	T
AF12	PB35B	5	PCLKC5_0/BDQ33	C	PB35B	5	PCLKC5_0/BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
GND	GNDIO5	-			GNDIO5	-		
AD15	PB40A	4	PCLKT4_0/BDQ42	T	PB40A	4	PCLKT4_0/BDQ42	T
VCCIO	VCCIO4	4			VCCIO4	4		
AC15	PB40B	4	PCLKC4_0/BDQ42	C	PB40B	4	PCLKC4_0/BDQ42	C
AE13	PB41A	4	BDQ42	T	PB41A	4	BDQ42	T
AF13	PB41B	4	BDQ42	C	PB41B	4	BDQ42	C
AB17	PB42A	4	BDQS42	T	PB42A	4	BDQS42	T
GND	GNDIO4	-			GNDIO4	-		
Y15	PB42B	4	BDQ42	C	PB42B	4	BDQ42	C
AE14	PB43A	4	BDQ42	T	PB43A	4	BDQ42	T
AF14	PB43B	4	BDQ42	C	PB43B	4	BDQ42	C
AA16	PB44A	4	BDQ42	T	PB44A	4	BDQ42	T
VCCIO	VCCIO4	4			VCCIO4	4		
W15	PB44B	4	BDQ42	C	PB44B	4	BDQ42	C
AC17	PB45A	4	BDQ42	T	PB45A	4	BDQ42	T
AB16	PB45B	4	BDQ42	C	PB45B	4	BDQ42	C
AE15	PB46A	4	BDQ42	T	PB46A	4	BDQ42	T
GND	GNDIO4	-			GNDIO4	-		
AF15	PB46B	4	BDQ42	C	PB46B	4	BDQ42	C
AE16	PB47A	4	BDQ51	T	PB47A	4	BDQ51	T
AF16	PB47B	4	BDQ51	C	PB47B	4	BDQ51	C
Y16	PB48A	4	BDQ51	T	PB48A	4	BDQ51	T
AB18	PB48B	4	BDQ51	C	PB48B	4	BDQ51	C
AD17	PB49A	4	BDQ51	T	PB49A	4	BDQ51	T
AD18	PB49B	4	BDQ51	C	PB49B	4	BDQ51	C
VCCIO	VCCIO4	4			VCCIO4	4		
AC18	PB50A	4	BDQ51	T	PB50A	4	BDQ51	T
AD19	PB50B	4	BDQ51	C	PB50B	4	BDQ51	C
GND	GNDIO4	-			GNDIO4	-		
AC19	PB51A	4	BDQS51	T	PB51A	4	BDQS51	T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AB24	PR87B	8	D3	C
GND	GNDIO4	-		
AB23	PR87A	8	D4	T
AB25	PR86B	8	D5	C
AB26	PR86A	8	D6	T
AC27	PR85B	8	D7/SPID0	C
VCCIO	VCCIO8	8		
AB27	PR85A	8	DI/CSSPI0N	T
AD29	PR84B	8	DOUT/CSON	C
AD30	PR84A	8	BUSY/SISPI	T
AA25	PR83B	3	RDQ80	C
GND	GNDIO3	-		
AA23	PR83A	3	RDQ80	T
AC29	PR82B	3	RDQ80	C (LVDS)*
AC30	PR82A	3	RDQ80	T (LVDS)*
AA26	PR81B	3	RDQ80	C
VCCIO	VCCIO3	3		
AA24	PR81A	3	RDQ80	T
AB29	PR80B	3	RDQ80	C (LVDS)*
AB30	PR80A	3	RDQS80	T (LVDS)*
GND	GNDIO3	-		
Y23	PR79B	3	RDQ80	C
Y25	PR79A	3	RDQ80	T
AA27	PR78B	3	RDQ80	C (LVDS)*
AA28	PR78A	3	RDQ80	T (LVDS)*
VCCIO	VCCIO3	3		
Y24	PR77B	3	RLM0_GPLLC_FB_A/RDQ80	C
Y26	PR77A	3	RLM0_GPLLT_FB_A/RDQ80	T
AA29	PR76B	3	RLM0_GPLLC_IN_A**/RDQ80	C (LVDS)*
AA30	PR76A	3	RLM0_GPLLT_IN_A**/RDQ80	T (LVDS)*
R22	RLM0_PLLCAP	3		
W23	PR74B	3	RLM0_GDLLC_FB_A/RDQ71	C
W25	PR74A	3	RLM0_GDLLT_FB_A/RDQ71	T
GND	GNDIO3	-		
Y27	PR73B	3	RLM0_GDLLC_IN_A**/RDQ71	C (LVDS)*
Y28	PR73A	3	RLM0_GDLLT_IN_A**/RDQ71	T (LVDS)*
W24	PR72B	3	RDQ71	C
W26	PR72A	3	RDQ71	T
VCCIO	VCCIO3	3		
Y29	PR71B	3	RDQ71	C (LVDS)*
Y30	PR71A	3	RDQS71	T (LVDS)*
V25	PR70B	3	RDQ71	C
GND	GNDIO3	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

	LFE2M50E/SE				LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA6	NC	-			PL79B	6	LDQ82	C
AB4	NC	-			PL80A	6	LDQ82	T (LVDS)*
-	-	-			VCCIO6	6		
AB5	NC	-			PL80B	6	LDQ82	C (LVDS)*
AA8	NC	-			PL81A	6	LDQ82	T
AA9	NC	-			PL81B	6	LDQ82	C
AC1	PL62A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL82A	6	LLM0_GPLLT_IN_A**/LDQS82	T (LVDS)*
GNDIO	GNDIO6	-			GNDIO6	-		
AC2	PL62B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL82B	6	LLM0_GPLLC_IN_A**/LDQ82	C (LVDS)*
AC4	PL63A	6	LLM0_GPLLT_FB_A	T	PL83A	6	LLM0_GPLLT_FB_A/LDQ82	T
AC3	PL63B	6	LLM0_GPLLC_FB_A	C	PL83B	6	LLM0_GPLLC_FB_A/LDQ82	C
VCCIO	VCCIO6	6			VCCIO6	6		
AC7	PL64A	6	LLM0_GDLLT_IN_A**	T (LVDS)*	PL84A	6	LLM0_GDLLT_IN_A**/LDQ82	T (LVDS)*
AC6	PL64B	6	LLM0_GDLLC_IN_A**	C (LVDS)*	PL84B	6	LLM0_GDLLC_IN_A**/LDQ82	C (LVDS)*
AC5	PL65A	6	LLM0_GDLLT_FB_A	T	PL85A	6	LLM0_GDLLT_FB_A/LDQ82	T
AD3	PL65B	6	LLM0_GDLLC_FB_A	C	PL85B	6	LLM0_GDLLC_FB_A/LDQ82	C
GNDIO	GNDIO6	-			GNDIO6	-		
AB8	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
AD2	PL67A	6	LDQ71	T (LVDS)*	PL87A	6		T
AD1	PL67B	6	LDQ71	C (LVDS)*	PL87B	6		C
AE2	TCK	-			TCK	-		
AE1	TDI	-			TDI	-		
AF2	TMS	-			TMS	-		
AF1	TDO	-			TDO	-		
AG1	VCCJ	-			VCCJ	-		
AH1	VCC	-			LLC_SQ_VCCRX3	14		
AK2	PB11A	5	BDQ15	T	LLC_SQ_HDINP3	14		T
AJ1	NC	-			LLC_SQ_VCCIB3	14		
AJ2	PB11B	5	BDQ15	C	LLC_SQ_HDINN3	14		C
AH4	VCC	-			LLC_SQ_VCCTX3	14		
AK5	PB13A	5	BDQ15	T	LLC_SQ_HDOUTP3	14		T
AK4	NC	-			LLC_SQ_VCCOB3	14		
AJ5	PB13B	5	BDQ15	C	LLC_SQ_HDOUTN3	14		C
AH5	VCC	-			LLC_SQ_VCCTX2	14		
AJ6	PB14B	5	BDQ15	C	LLC_SQ_HDOUTN2	14		C
AH6	NC	-			LLC_SQ_VCCOB2	14		
AK6	PB14A	5	BDQ15	T	LLC_SQ_HDOUTP2	14		T
AH2	VCC	-			LLC_SQ_VCCRX2	14		
AJ3	PB12B	5	BDQ15	C	LLC_SQ_HDINN2	14		C
AH3	NC	-			LLC_SQ_VCCIB2	14		
AK3	PB12A	5	BDQ15	T	LLC_SQ_HDINP2	14		T
AH7	VCC	-			LLC_SQ_VCCP	14		
AG7	PB15A	5	BDQS15	T	LLC_SQ_REFCLKP	14		T
AF7	PB15B	5	BDQ15	C	LLC_SQ_REFCLKN	14		C
AJ7	VCCAUX	-			LLC_SQ_VCCAUX33	14		
AK11	PB18A	5	BDQ15	T	LLC_SQ_HDINP1	14		T
AH11	NC	-			LLC_SQ_VCCIB1	14		
AJ11	PB18B	5	BDQ15	C	LLC_SQ_HDINN1	14		C

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E13	PT28A	0		T	PT37A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
GNDIO	GNDIO0	-			GNDIO0	-		
J12	PT5B	0		C	PT31B	0		C
GNDIO	GNDIO0	-			-	-		
VCCIO	VCCIO0	0			VCCIO0	0		
H10	PT5A	0		T	PT31A	0		T
E12	PT4B	0		C	PT30B	0		C
D11	PT4A	0		T	PT30A	0		T
H11	PT3B	0		C	PT29B	0		C
F11	PT3A	0		T	PT29A	0		T
C13	VCC	-			ULC_SQ_VCCRX0	11		
A12	PT19A	0		T	ULC_SQ_HDINP0	11		T
B13	NC	-			ULC_SQ_VCCIB0	11		
B12	PT19B	0		C	ULC_SQ_HDINN0	11		C
C10	VCC	-			ULC_SQ_VCCTX0	11		
A9	PT17A	0		T	ULC_SQ_HDOUTP0	11		T
A10	NC	-			ULC_SQ_VCCOB0	11		
B9	PT17B	0		C	ULC_SQ_HDOUTN0	11		C
C9	VCC	-			ULC_SQ_VCCTX1	11		
B8	PT18B	0		C	ULC_SQ_HDOUTN1	11		C
C8	NC	-			ULC_SQ_VCCOB1	11		
A8	PT18A	0		T	ULC_SQ_HDOUTP1	11		T
C12	VCC	-			ULC_SQ_VCCRX1	11		
B11	PT16B	0		C	ULC_SQ_HDINN1	11		C
C11	NC	-			ULC_SQ_VCCIB1	11		
A11	PT16A	0		T	ULC_SQ_HDINP1	11		T
B7	VCCAUX	-			ULC_SQ_VCCAUX33	11		
E7	PT15B	0		C	ULC_SQ_REFCLKN	11		C
D7	PT15A	0		T	ULC_SQ_REFCLKP	11		T
C7	VCC	-			ULC_SQ_VCCP	11		
A3	PT12A	0		T	ULC_SQ_HDINP2	11		T
C3	NC	-			ULC_SQ_VCCIB2	11		
B3	PT12B	0		C	ULC_SQ_HDINN2	11		C
C2	VCC	-			ULC_SQ_VCCRX2	11		
A6	PT14A	0		T	ULC_SQ_HDOUTP2	11		T
C6	NC	-			ULC_SQ_VCCOB2	11		
B6	PT14B	0		C	ULC_SQ_HDOUTN2	11		C
C5	VCC	-			ULC_SQ_VCCTX2	11		
B5	PT13B	0		C	ULC_SQ_HDOUTN3	11		C
A4	NC	-			ULC_SQ_VCCOB3	11		
A5	PT13A	0		T	ULC_SQ_HDOUTP3	11		T
C4	VCC	-			ULC_SQ_VCCTX3	11		
B2	PT11B	0		C	ULC_SQ_HDINN3	11		C
B1	NC	-			ULC_SQ_VCCIB3	11		
A2	PT11A	0		T	ULC_SQ_HDINP3	11		T
C1	VCC	-			ULC_SQ_VCCRX3	11		
L12	VCC	-			VCC	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
D19	PT93B	1		C
E18	PT93A	1		T
D18	PT92B	1		C
C17	PT92A	1		T
A17	PT91B	1		C
B17	PT91A	1		T
GNDIO	GNDIO1	-		
VCCIO	VCCIO1	1		
J18	PT75B	1		C
J19	PT75A	1		T
H17	PT74B	1		C
J17	PT74A	1		T
F18	PT73B	1		C
F17	PT73A	1		T
GNDIO	GNDIO1	-		
A16	PT72B	1		C
B16	PT72A	1		T
G17	PT71B	1		C
G16	PT71A	1		T
VCCIO	VCCIO1	1		
H16	PT70B	1		C
F16	PT70A	1		T
J16	PT69B	1		C
G15	PT69A	1		T
GNDIO	GNDIO1	-		
C16	PT68B	1		C
D16	PT68A	1		T
J15	PT67B	1		C
H15	PT67A	1		T
VCCIO	VCCIO1	1		
A15	PT66B	1	VREF2_1	C
B15	PT66A	1	VREF1_1	T
F15	PT65B	1	PCLKC1_0	C
E16	PT65A	1	PCLKT1_0	T
C15	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-		
D15	PT64A	0	PCLKT0_0	T
C14	PT63B	0	VREF2_0	C
E15	PT63A	0	VREF1_0	T
G14	PT62B	0		C
VCCIO	VCCIO0	0		
J14	PT62A	0		T
F14	PT61B	0		C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
M23	GND	-		
M8	GND	-		
N14	GND	-		
N15	GND	-		
N16	GND	-		
N17	GND	-		
N27	GND	-		
N4	GND	-		
P11	GND	-		
P13	GND	-		
P14	GND	-		
P15	GND	-		
P16	GND	-		
P17	GND	-		
P18	GND	-		
P20	GND	-		
R10	GND	-		
R11	GND	-		
R13	GND	-		
R14	GND	-		
R15	GND	-		
R16	GND	-		
R17	GND	-		
R18	GND	-		
R20	GND	-		
R21	GND	-		
R24	GND	-		
R7	GND	-		
T10	GND	-		
T11	GND	-		
T13	GND	-		
T14	GND	-		
T15	GND	-		
T16	GND	-		
T17	GND	-		
T18	GND	-		
T20	GND	-		
T21	GND	-		
T24	GND	-		
T7	GND	-		
U11	GND	-		
U13	GND	-		
U14	GND	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
V18	VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
*** These sysCONFIG pins are dedicated I/O pins for configuration. The outpus are actively driven during normal device operation.
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

Date	Version	Section	Change Summary
June 2013 (cont.)	04.0 (cont.)	DC and Switching Characteristics	sysCLOCK SPLL Timing table – Corrected signal names for t_{RST} parameter.
			LatticeECP2/M sysCONFIG Port Timing Specifications table – added t_{SUMCDI} and t_{HMCDI} parameters.
September 2013	04.1	Architecture	Updated Selectable Master Clock (CCLK) Frequencies during Configuration table.
		DC and Switching Characteristics	Added information on f_{MAXSPI} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.